

## Engineering Science Seminar 2015 --- Seeking Participants

**Dates:** November 17th (Tue) to 20th (Fri), 2015

**Place:** Graduate School of Engineering Science, Osaka University  
1-3, Machikaneyama, Toyonaka, Osaka, 560-8531, Japan

**Purpose:** The program aims for the development of human resources and contributing to the development of both countries. Besides, we provide preliminary experience for potential students to enroll in Osaka University.

**Contents:** (1) Lectures  
(2) Students' group discussions and presentations  
(3) Interviews with professors from Osaka University  
(4) Poster presentation at the International Symposium held on Nov. 17-18  
<http://thmat8.ess.sci.osaka-u.ac.jp/Meeting2015/>  
(5) Others (e.g. lab tour, hands-on learning activities)

**Financial support:** Airplane tickets and hotel fees will be paid by Osaka University.

### Requirements:

- (1) Applicants should understand the purpose of this program and participate in the discussions.
- (2) Participants should have or will obtain a passport and apply for a visa for a short-term stay in Japan.
- (3) Participants should take out travel insurance.

**Number of openings:** 6 students in total

**Deadline:** 12:00JST, Friday, Sep.25th, 2015

**Application:** Send email to [ESS2015@cpair.es.osaka-u.ac.jp](mailto:ESS2015@cpair.es.osaka-u.ac.jp) with title 'ESSeminar2015(your name)' and attach your application.

**Notice:** For graduate and under graduate students, before sending an application to us, please be sure to get permission from your supervisor.

**Screening:** We will select participants by considering various aspects like contents of the application form, language ability, affiliation, academic year, delegation balance, interview and paper test.

The schedule is as follows:

Sep. 25, deadline of application

Sep. 25-Oct. 5 Screening of application documents

Oct. 11-16, Screening by interview and paper based test at Hanoi and HCM

Oct. 19-21, VISA application

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